# Multilayer Ceramic Capacitor Multicomp PRO





### **RoHS Compliant**

#### Features:

· For General Purpose

Capacitor Dielectric Material: Multilayer Ceramic

Termination: Radial Leaded

Lead Pitch: 2.54mm

### **Ordering informations:**

MC	0805	В	104	K	500	2.54MM	
$\downarrow$	$\downarrow$	$\downarrow$	$\downarrow$	$\downarrow$	$\downarrow$	↓	
Α	В	С	D	Е	F	G	

Α
Product Type

В					
Unit : Inches					
Chip Size (L×W)					
Code Chip					
0805	0.08 × 0.05				
1206	0.12 × 0.06				

**Rated Voltage** The code meaning is same as capacitance. For Example: 101=100V 500=50V

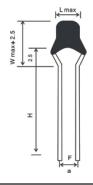
С						
Dielectric						
N COG (NPO						
В	X7R					
Υ	Y5V					

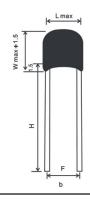
G					
Packaging Style					
Ammo	2.54mm				
AIIIIII	5.08mm				

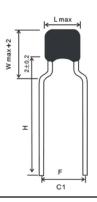
D					
Capacitance					
First two digits are significant third digit is number of zeros. For Example: 104=100000pF					
5R6=5.6pF					

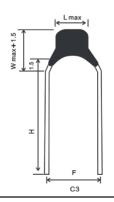
E						
Tolerance						
С	±0.25pF					
D	±0.5pF					
J	±5%					
K	±10%					
М	±20%					
Z	+80% -20%					

#### **Dimensions:**











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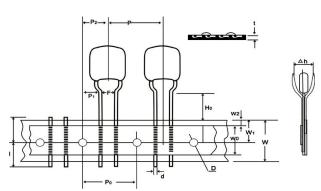
multicomp PRO

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Size Code S		Dimensions (mm)						Capacitance (pF)		
	Shape	F (±0.5)	H (±1)	L max.	W max.	T max.	Voltage	NPO	X7R	Y5V
	а	2.54	5							
	b	2.54	10				25V	0R5~332	331~104	100 105
0805	C1	5.08	5 / 10	4.2	3.8	3.8	50V	0R5~222	331~104	103~105
	C2	5.08	5				100V	0R5~102	331~104	103~684
	C3	5.08	5 / 10							
	а	2.54					25V	0R5~682	102~224	400 405
1206	b	3.50	10	5	4.5	3.8	50V	0R5~472	102~104	103~125
	C1	5.08					100V	0R5~392	102~105	103~105

#### **Packaging Style:**



Description	Symbol	Dimensions (mm)	Remarks
Pitch Of Component	Р	12.7 ±1.0	Cumulative Pitch Error : ±1mm /20 Pitches
Feedhold Pitch	PO	12.7 ±0.3	For F:5.08, 5.1±0.7 For F:2.54
Feed Hold Center To Lead	P1	3.85 ±0.7	
Feed Hold Centre To Component Centre	P2	8.35 ±1.3	To Lead Tip Within TOL
Lead To Lead Spacing	F	5.08 +0.8/-0.2 or 2.5 +0.8/-0.2	The alignment form the center of the lead is ±1.0mm
Component Alignment, F-R	ΔΗ	2 Max.	
Tape Width	W	18 ±1	
Adhesive Tape Width	W0	12 ±1	
Hole Position	W1	9 ±0.5	Adhesive Tape Must Not Protrude From Bade Paper
Adhesive Tape Position	W2	3 Max	6.5 <= H0-W1
Lead-Wire Clinch Height	H0	15-20 ±0.5	
Component Height	H1	32.25 Max.	
Feed Hole Diameter	D0	4 ±0.3	
Total Tape Thickness	Т	0.7 ±0.2	

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